



# 1.0A MOSFET/IGBT Gate Driver Optocoupler

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## Features

- Peak Output Current :  $I_{OP} = \pm 1.0A$  (max)
- Threshold Input Current:  $I_{FLH} = 5\text{ mA}$  (max)
- Common mode transient immunity :  $\pm 25kV/\mu s$  (min)
- RoHS and REACH Compliance
- MSL class 1
- Regulatory Approvals
  - ✓ UL - UL1577 (E364000)
  - ✓ VDE - EN60747-5-5(VDE0884-5)
  - ✓ CQC – GB4943.1, GB8898(14001104999)
  - ✓ IEC62368 (FI/41119)

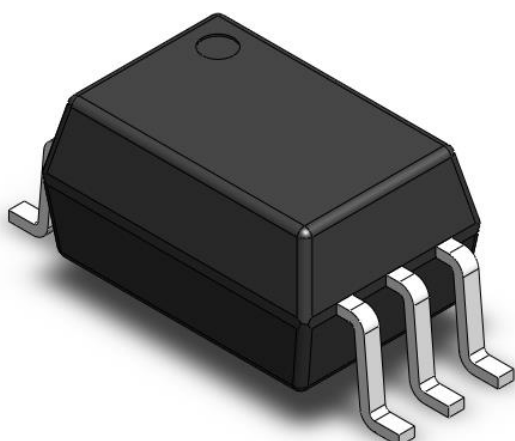
## Description

The CTS314 consists of a GaAsP LED optically coupled to an integrated circuit with a power output stage. This optocoupler is ideally suited for driving power IGBTs and MOSFETs used in motor control inverter applications. The high operating voltage range of the output stage provides the drive voltages required by gate controlled devices.

## Applications

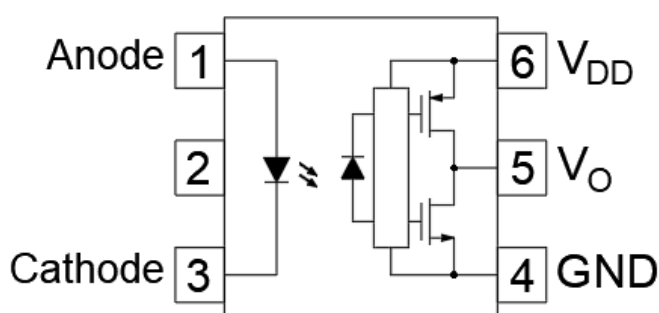
- Isolated IGBT/Power MOSFET gate drive
- Industrial Inverter
- AC brushless and DC motor drives
- Induction Heating

## Package Outline



Note: Different lead forming options available. See package dimension.

## Schematic



## Truth Table

LED	$V_{CC}-V_{EE}$ Positive Going	$V_{CC}-V_{EE}$ Negative Going	Output
Off	0 to 30 V	0 to 30V	Low
On	0 to 11.0V	0 to 9.5V	Low
On	11.0 to 13.5V	9.5 to 12V	Transition
On	13.5 to 30V	12 to 30V	High



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[www.ct-micro.com](http://www.ct-micro.com)**Absolute Maximum Ratings**  $T_A = 25^{\circ}\text{C}$ , unless otherwise specified

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameters	Ratings	Units	Notes
$V_{\text{ISO}}$	Isolation voltage (AC, 1 minute, 40 ~ 60% R.H.)	5000	$V_{\text{RMS}}$	1
$T_{\text{OPR}}$	Operating temperature	-40 ~ +100	$^{\circ}\text{C}$	
$T_{\text{STG}}$	Storage temperature	-55 ~ +125	$^{\circ}\text{C}$	
$T_{\text{SOL}}$	Soldering temperature (For 10 seconds)	260	$^{\circ}\text{C}$	2
$P_T$	Total Power Dissipation	300	mW	
<b>Emitter</b>				
$I_F$	Forward current	25	mA	
$I_{\text{FP}}$	Peak forward current (50% duty, 1ms P.W)	1	A	
$V_R$	Reverse voltage	5	V	
<b>Detector</b>				
$P_O$	Output Power dissipation	250	mW	
$V_{\text{O(PEAK)}}$	Peak Output Voltage	35	V	3
$I_{\text{OPH}}$	Output High Peak Current	1	A	4
$I_{\text{OPL}}$	Output Low Peak Current	1	A	4
$V_{\text{CC}}$	Supply voltage	35	V	

## Notes

1. AC for 1 minute, RH = 40 ~ 60%.
2. For 10 second peak
3. The  $V_{\text{O(PEAK)}}$  voltage CAN NOT BE high than  $V_{\text{CC}}$ .
4. The  $I_O$  maximum pulse width = 10 us, maximum duty cycle = 0.2%.



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## Electrical Characteristics

Over recommended operating conditions  $T_A = -40$  to  $100$  °C. Typical values are measured at  $V_{CC}=30V$ ,  $V_{EE}=GND$ ,  $T_A = 25^\circ C$  (unless otherwise stated)

## Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$V_F$	Forward Voltage	$I_F = 10mA$	-	1.4	1.8	V	
$V_R$	Reverse Voltage	$I_R = 10\mu A$	5.0	-	-	V	
$\Delta V_F / \Delta T_A$	Temperature coefficient of forward voltage	$I_F = 10mA$	-	-1.7	-	mV/°C	

## Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$I_{CCL}$	Logic Low Supply Current	$I_F = 0mA$	-	1.5	3	mA	
$I_{CCH}$	Logic High Supply Current	$I_F = 10mA$	-	1.5	3		

## Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
$V_{OH}$	High Level Output Voltage	$I_F = 10mA$ , $I_O = -100mA$	$V_{CC} - 0.6$	$V_{CC} - 0.4$	-	V	
$V_{OL}$	Low Level Output Voltage	$I_F = 0mA$ , $I_O = 100mA$	-	0.25	0.4	V	
$I_{OPH}$	High Level Output Current	$V_O = V_{CC} - 2V$	-	-	-0.3	A	1
		$V_O = V_{CC} - 4V$	-	-	-0.9		1
$I_{OPL}$	Low Level Output Current	$V_O = V_{EE} + 2V$	0.3	-	-	A	1
		$V_O = V_{EE} + 4V$	0.9	-	-		1
$I_{FLH}$	Input Threshold Current	$I_O = 0mA$ , $V_O > 5V$	-	1.4	5.0	mA	
$V_{FHL}$	Input Threshold Voltage	$I_O = 0mA$ , $V_O < 5V$	0.8	-	-	V	
$V_{UVLO+}$	Under Voltage Lockout	$I_O = 10mA$ , $V_O > 5V$	6.9	7.8	8.7	V	
$V_{UVLO-}$	Threshold	$I_O = 10mA$ , $V_O < 5V$	5.9	6.7	7.5	V	
$UVLO_{HYS}$	Under Voltage Lockout Hysteresis		-	1.1	-	V	

## Notes

1. The  $I_O$  maximum pulse width = 10 us, maximum duty cycle = 0.2%.



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## Switching Characteristics

Symbol	Parameters	Test Conditions		Min	Typ	Max	Units	Notes
$T_{PHL}$	High to Low Propagation Delay	$R_g = 47\Omega$ , $C_g = 3\text{ nF}$ , $f = 10\text{ kHz}$ , Duty = 50%, $I_F = 10\text{ mA}$ , $V_{CC} = 30\text{V}$		100	160	300	ns	
$T_{PLH}$	Low to High Propagation Delay			100	130	300	ns	
PWD	Pulse Width Distortion			-	30	-	ns	
PDD	Propagation Delay Difference Between Any Two Parts or Channels			-100	-	100	ns	
$t_r$	Rise Time			-	20	100	ns	
$t_f$	Fall Time			-	20	100	ns	
$ CM_H $	Common Mode Transient High	$V_{CC} = 30\text{V}$ , $T_A = 25^{\circ}\text{C}$ ,	$I_F = 7.5\text{ mA}$	25	-	-	$\text{kV}/\mu\text{s}$	
$ CM_L $	Common Mode Transient Low	$V_{CM} = 1.5\text{ kV}$	$I_F = 0\text{ mA}$	25	-	-	$\text{kV}/\mu\text{s}$	



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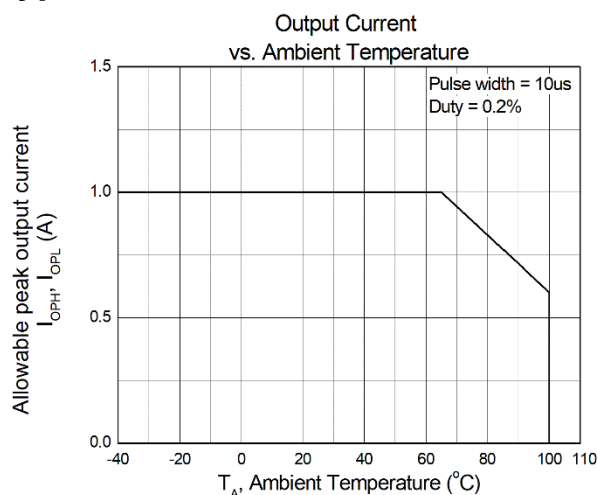
[www.ct-micro.com](http://www.ct-micro.com)Typical Characteristic Curves  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Figure 1

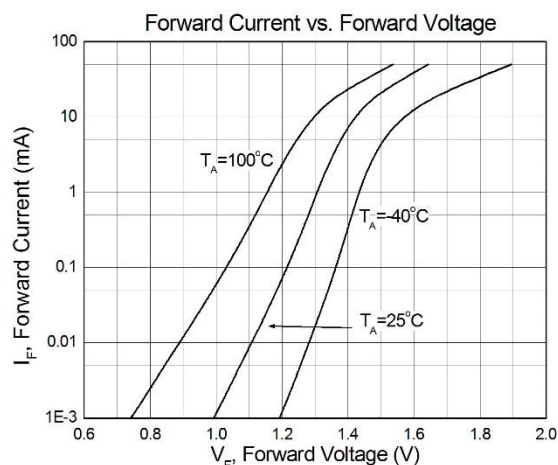


Figure 2

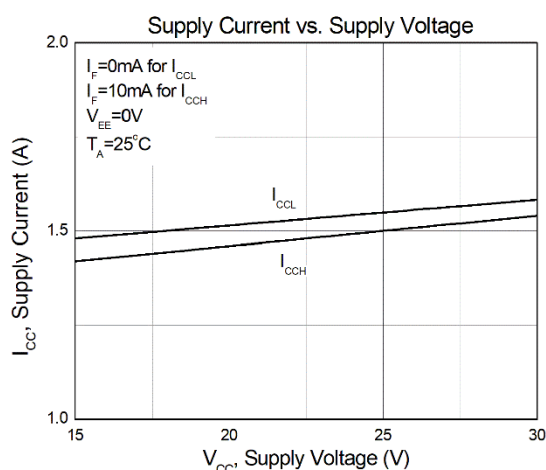


Figure 3

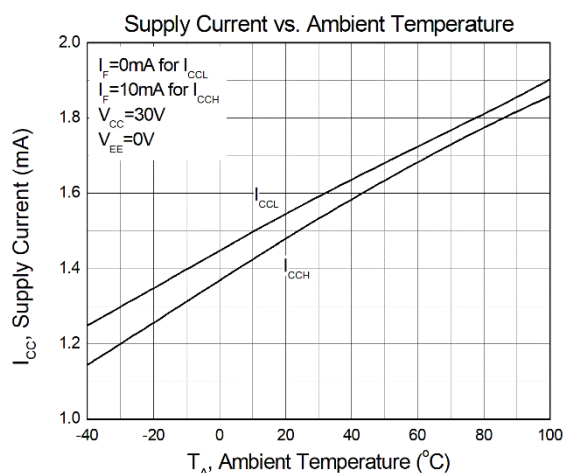


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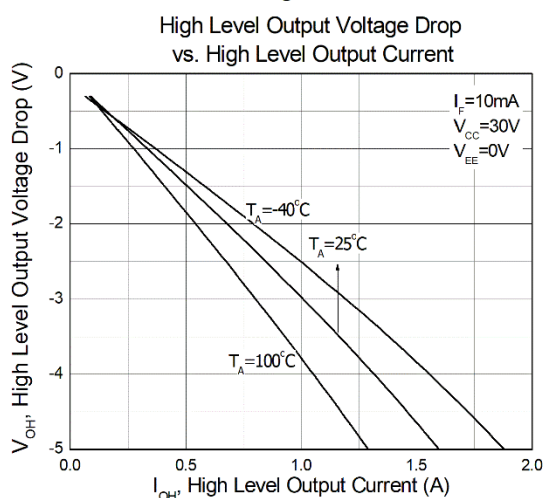


Figure 5

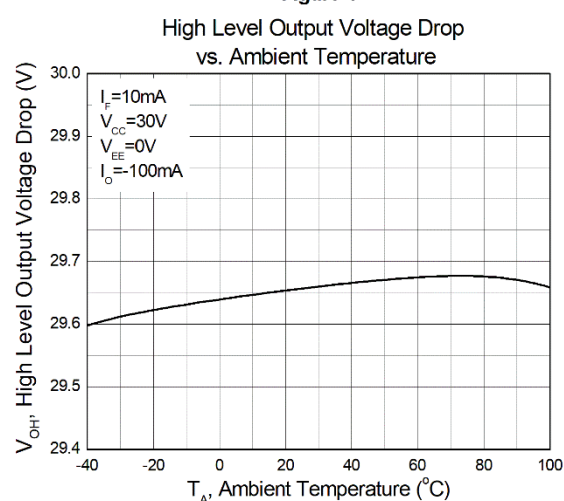


Figure 6



## 1.0A MOSFET/IGBT Gate Driver Optocoupler

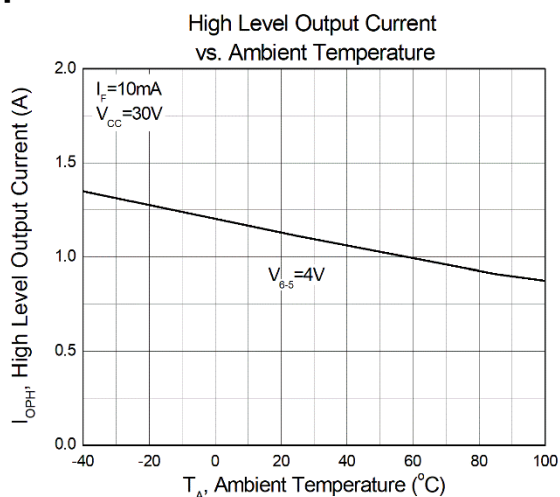
[www.ct-micro.com](http://www.ct-micro.com)Typical Characteristic Curves  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Figure 7

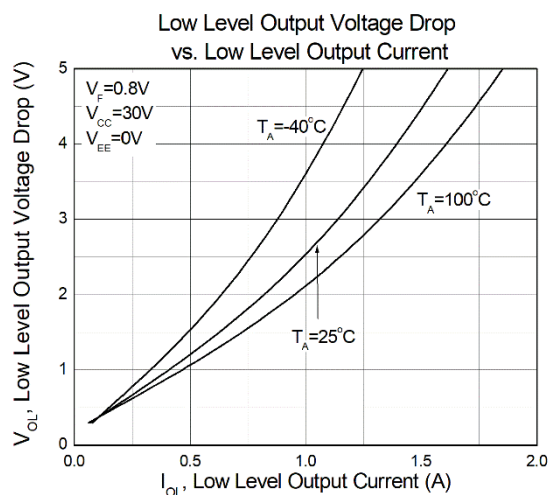


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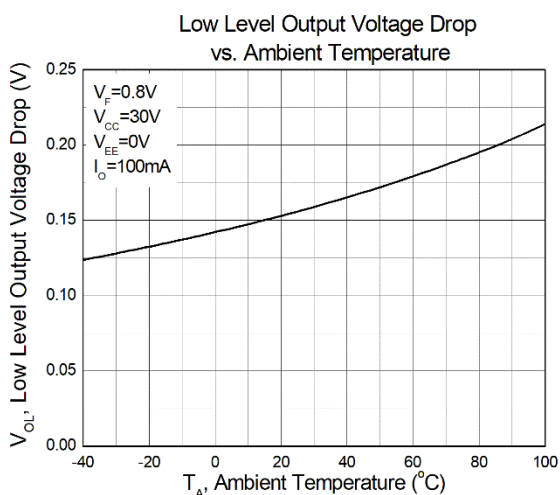


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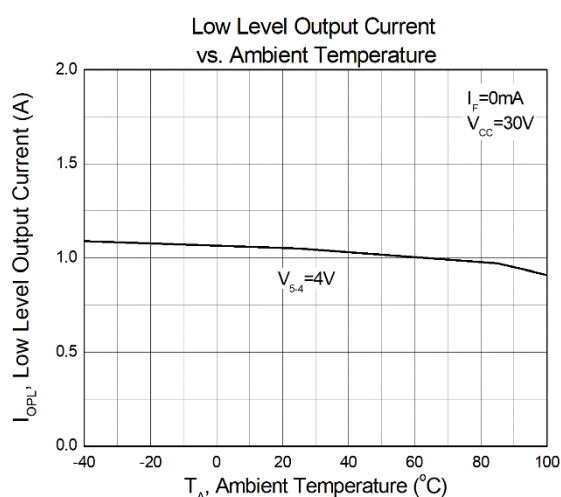


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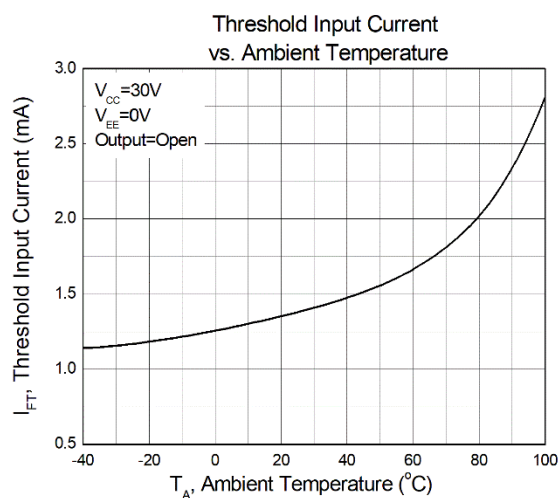


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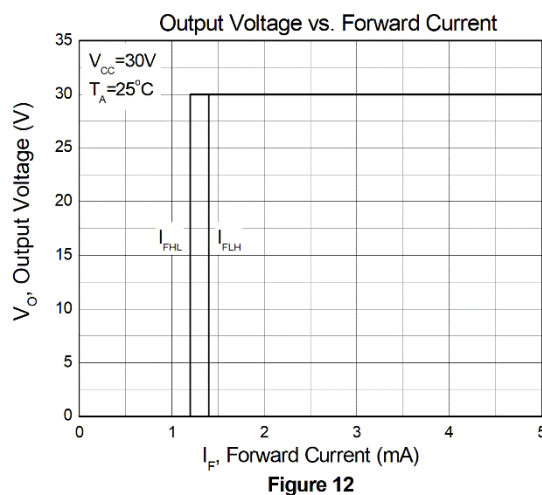


Figure 12



## 1.0A MOSFET/IGBT Gate Driver Optocoupler

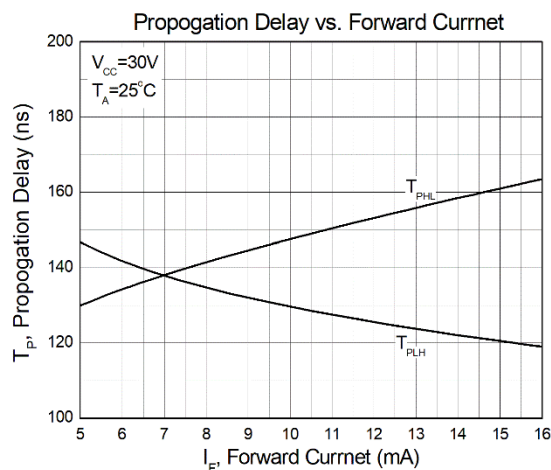
[www.ct-micro.com](http://www.ct-micro.com)Typical Characteristic Curves  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Figure 13

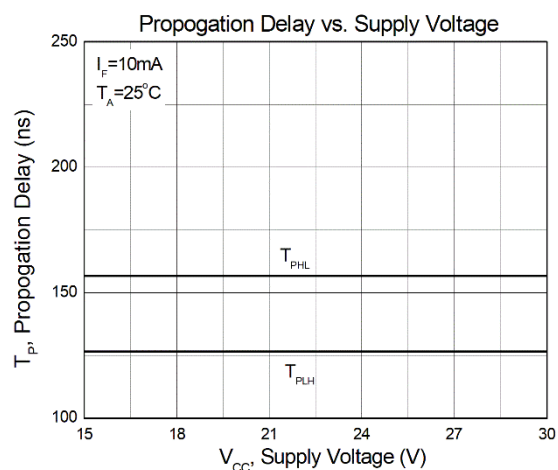


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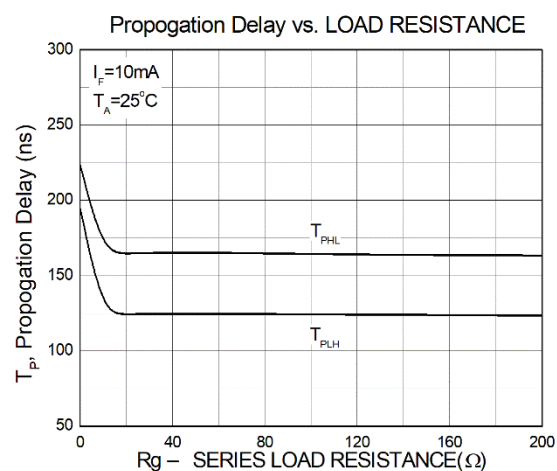


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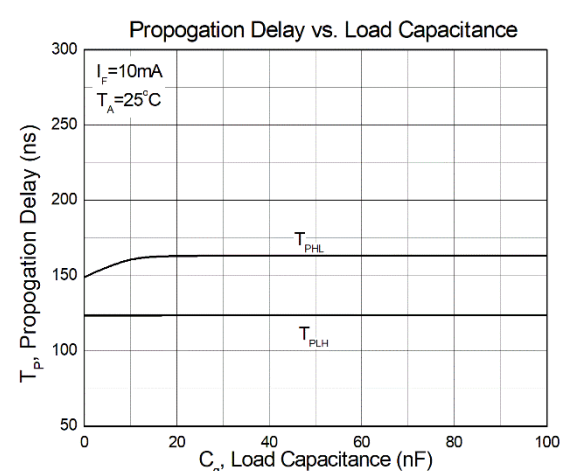


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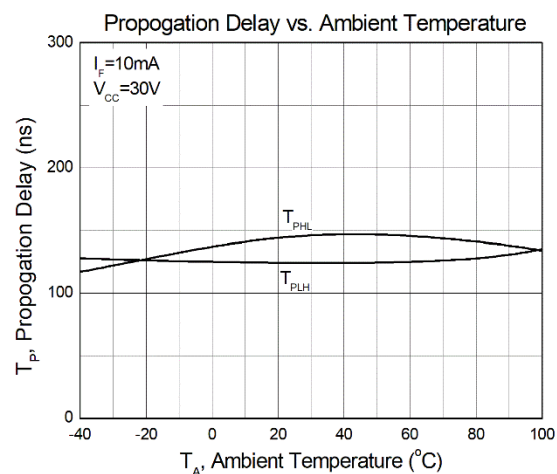
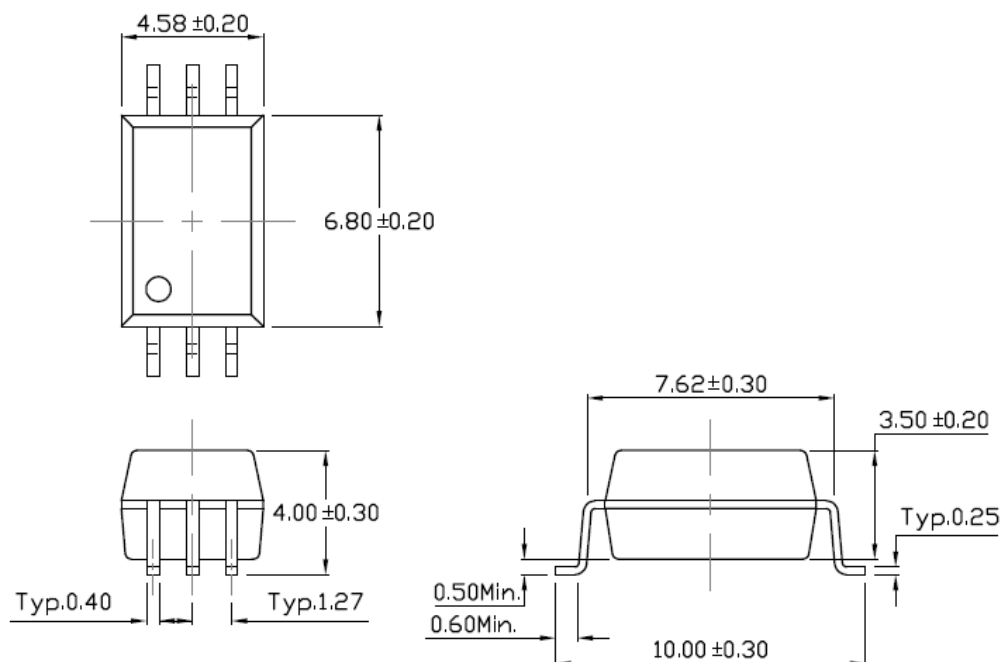


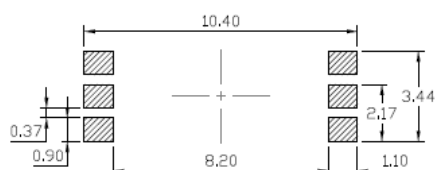
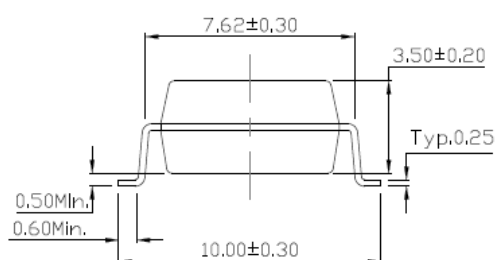
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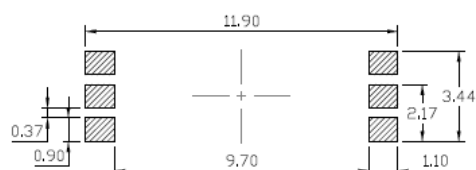
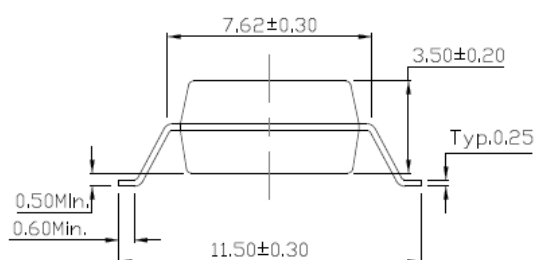
## 1.0A MOSFET/IGBT Gate Driver Optocoupler

[www.ct-micro.com](http://www.ct-micro.com)**Package Dimension** *Dimensions in mm unless otherwise stated***Surface Mount Lead Forming****Forming Option** *Dimensions in mm unless otherwise stated*

S Type



SM Type



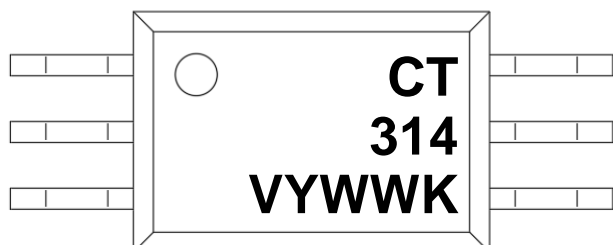




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## Marking Information



## Note:

CT : Denotes "CT Micro"  
314 : Part Number  
V : VDE Safety Mark Option (Blank or V)  
Y : One Digit Year Code  
WW : Two Digit Work Week  
K : Manufacturing Code

## Ordering Information

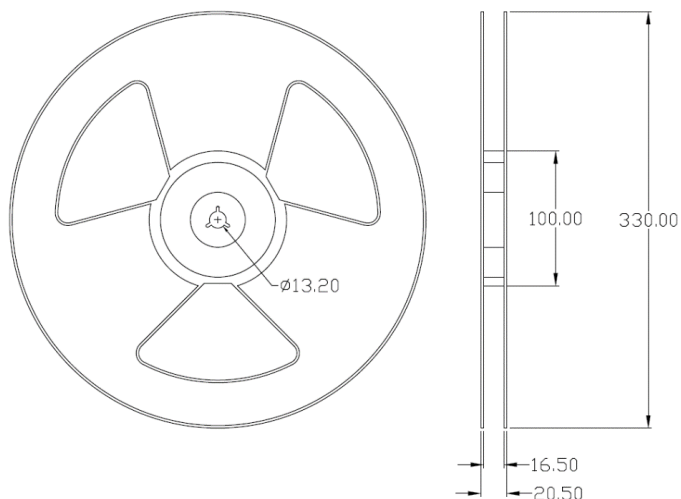
## CTS314(V)(Y)(Z)

CT = Denotes "CT Micro"  
S314 = Part Number  
V = VDE Safety Mark Option (Blank or V)  
Y = Lead Form Option (S or SM)  
Z = Tape and Reel Option (T1 or T2)

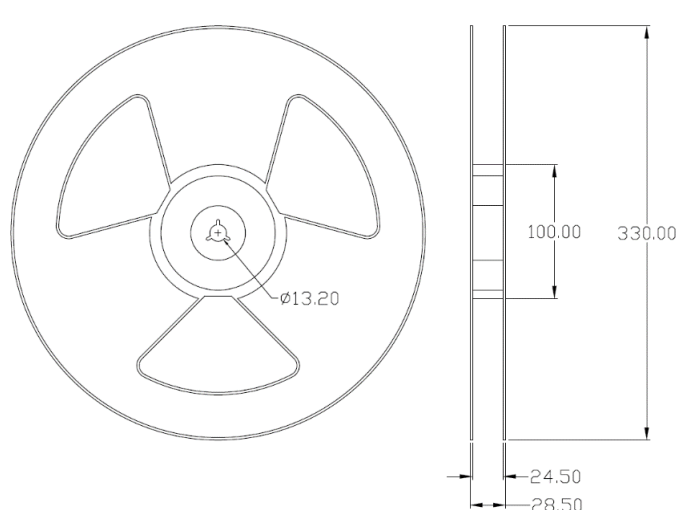
Option	Description	Quantity
T1	Surface Mount Lead Forming with Option 1 Taping	1500 Units/Reel
T2	Surface Mount Lead Forming with Option 2 Taping	1500 Units/Reel
M(T1)	Surface Mount (Gullwing) Lead Forming with Option 1 Taping	1500 Units/Reel
M(T2)	Surface Mount (Gullwing) Lead Forming with Option 2 Taping	1500 Units/Reel

Reel Dimension *All dimensions are in mm, unless otherwise stated*

## Option S(T1/T2)



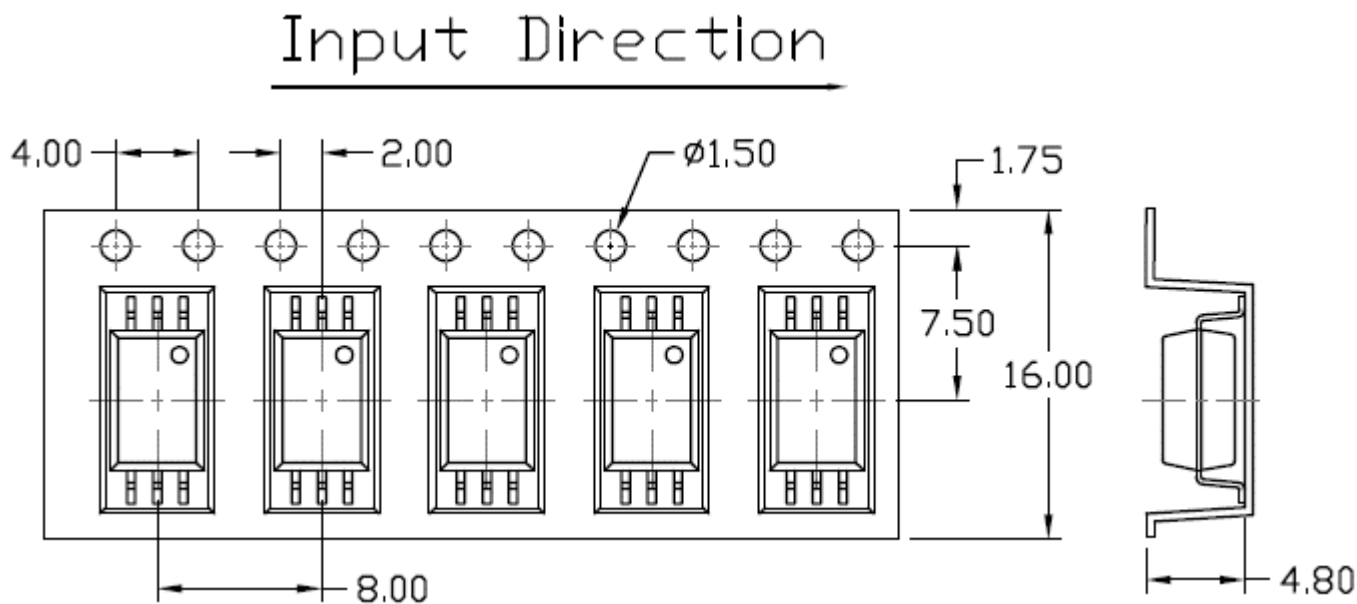
## Option M(T1/T2)



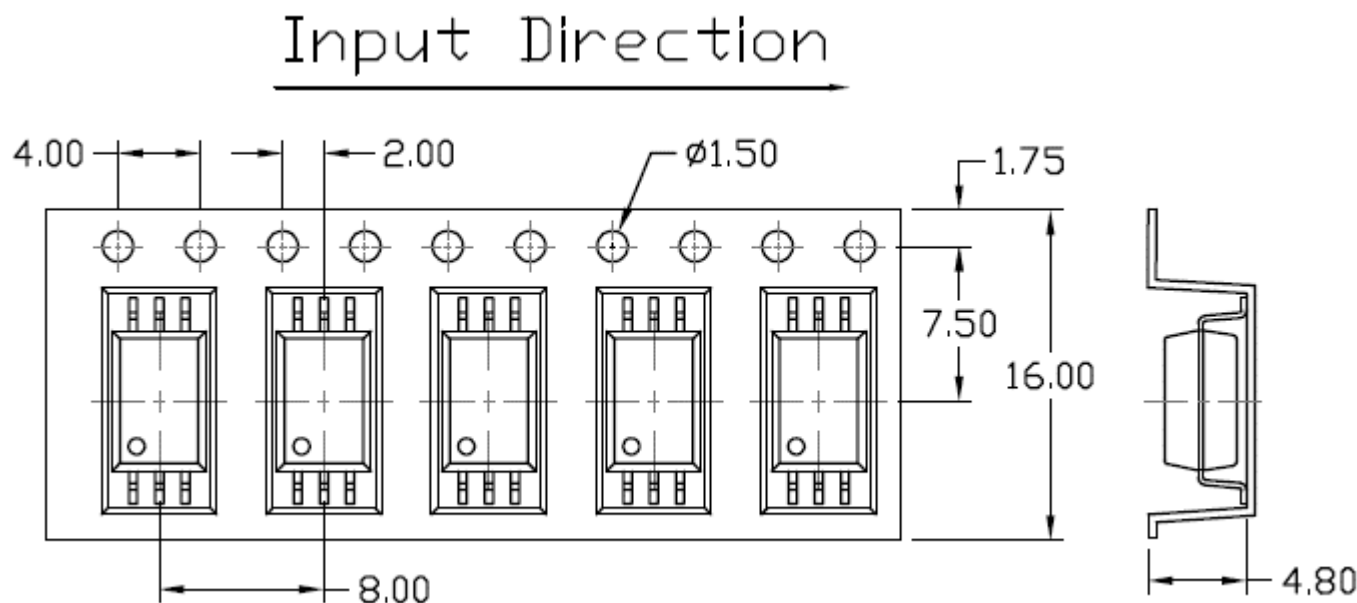


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### Option S(T1)



### Option S(T2)



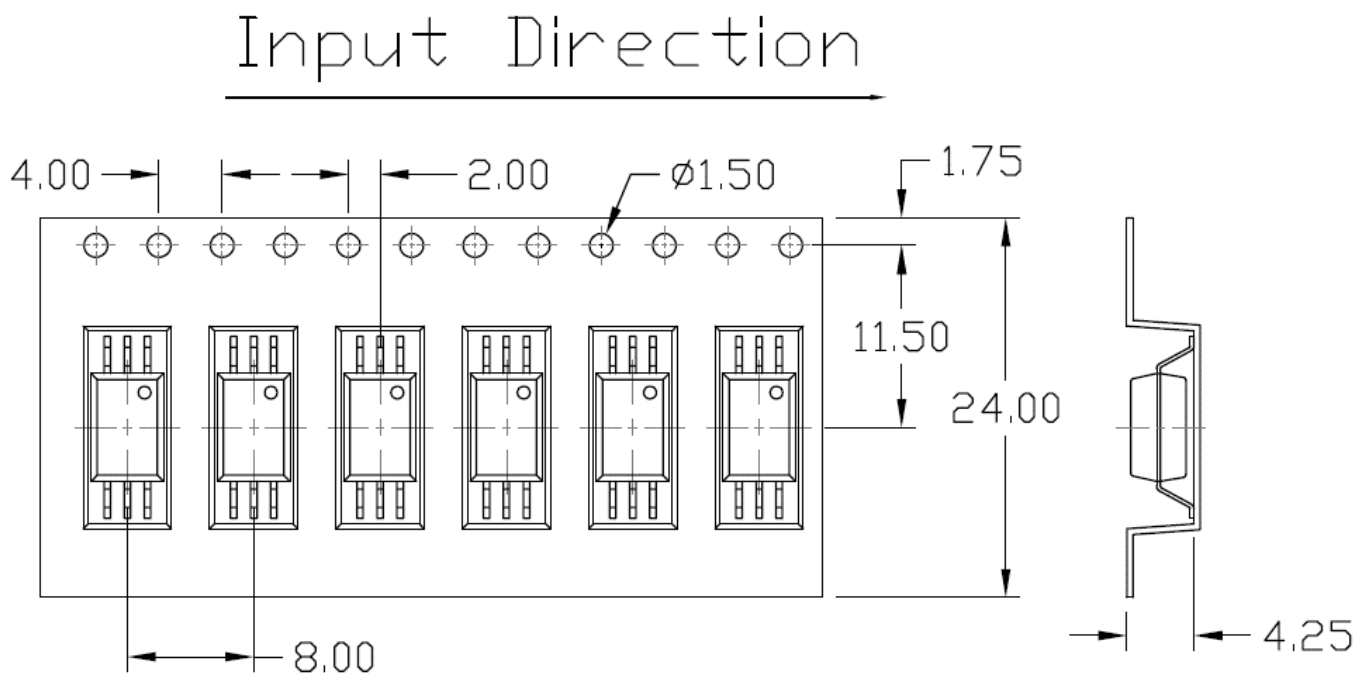


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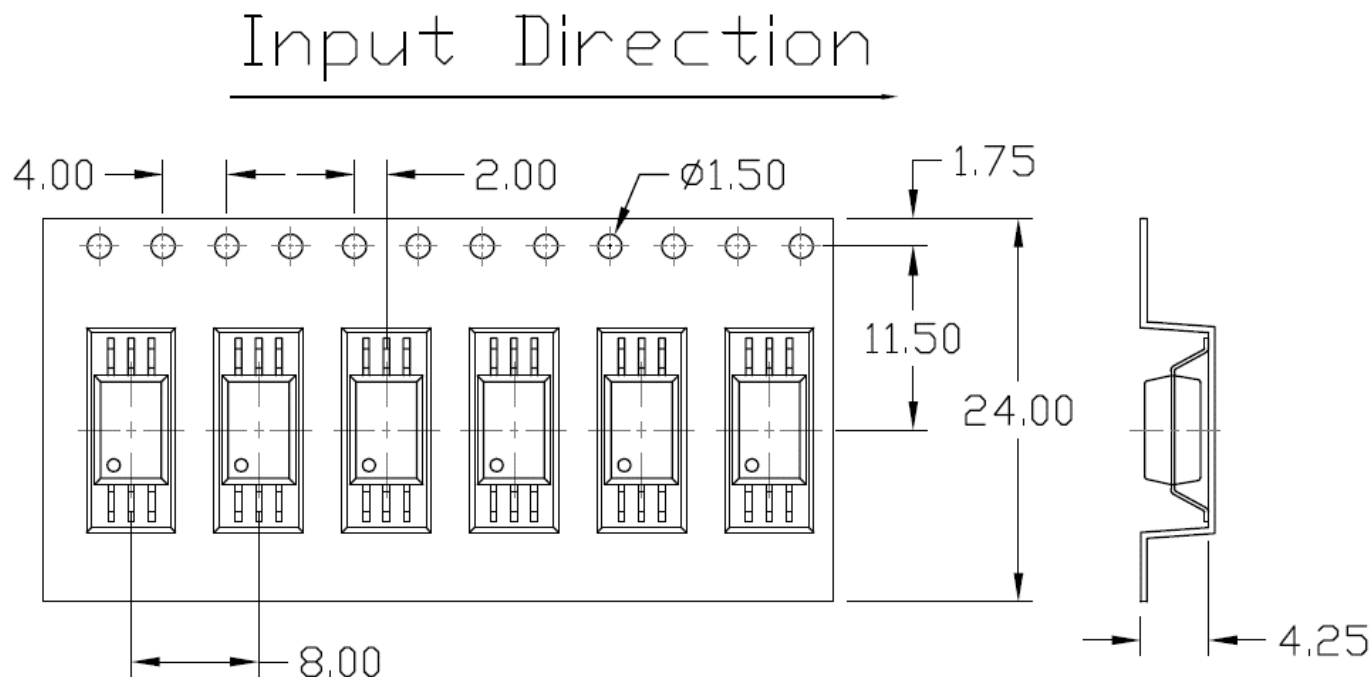
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### Option M(T1)



### Option M(T2)





## 1.0A MOSFET/IGBT Gate Driver Optocoupler

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### Solderability spec (Follow the JEDEC standard JESD22-B102)

Reflow Soldering: Immersed surface, other than the end of pin as cut-surface, must be covered by solder.

Solder-Bath: More than 95% of the electrode must be covered with solder.

### Wave soldering (Follow the JEDEC standard JESD22-A111)

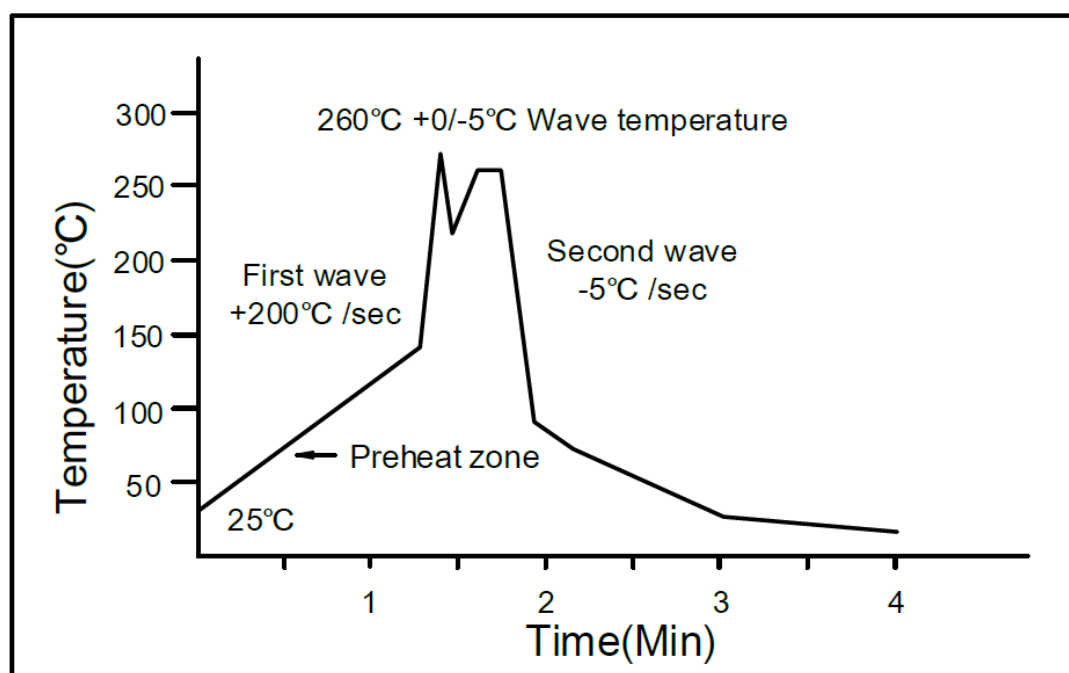
One time soldering is recommended within the condition of temperature.

Temperature:  $260 \pm 0/-5^{\circ}\text{C}$ .

Time: 10 sec.

Preheat temperature: 25 to  $140^{\circ}\text{C}$ .

Preheat time: 30 to 80 sec.



### Iron soldering (Follow the standard MIL-STD 202G, Method 210F)

Allow single lead soldering in every single process.

One time soldering is recommended. Temperature:  $350 \pm 10^{\circ}\text{C}$

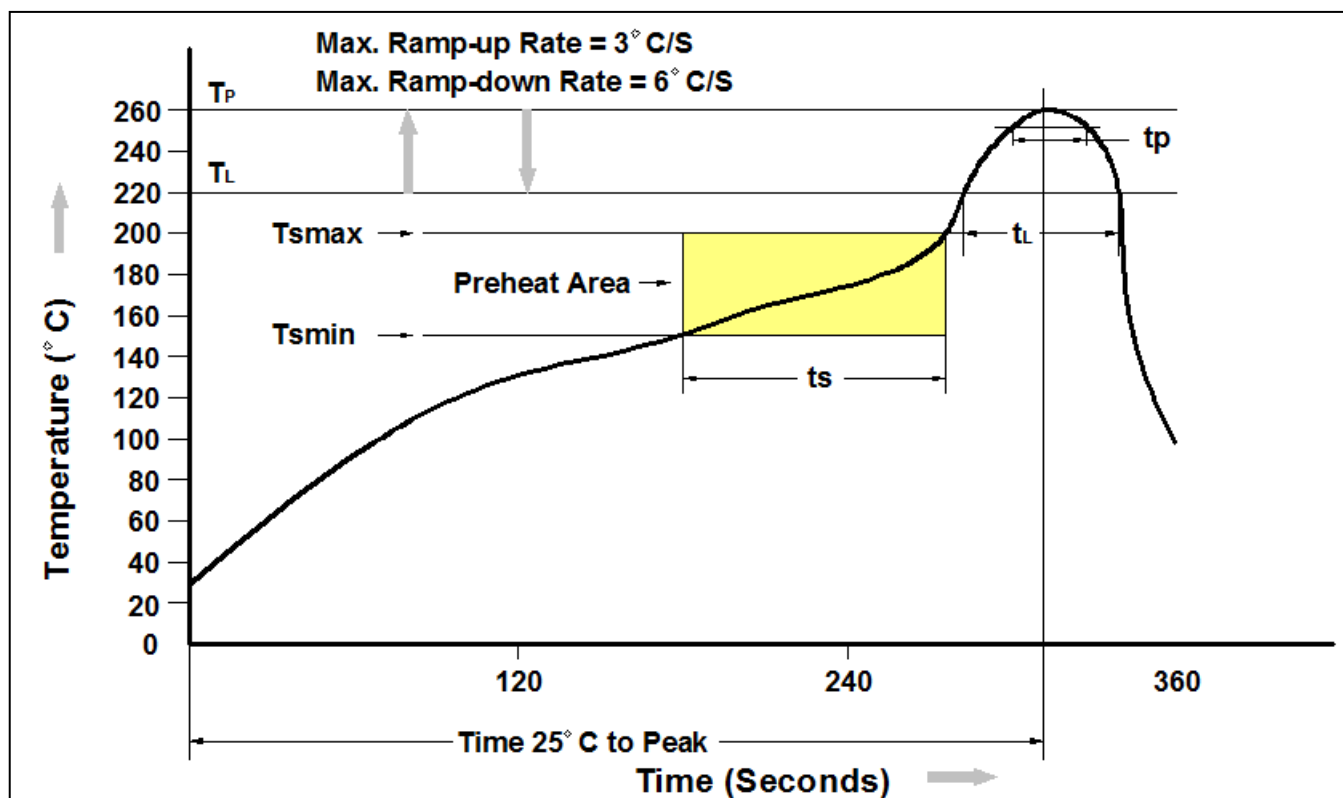
Time: 5 sec max.



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## Reflow Profile (Follow the JEDEC standard J-STD-020)



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (tL to tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tP) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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2. *A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.*